

Application of:
Andreas Huschka, Wolfram Kluge
and Uwe Hahn

Filed: February 12, 2004

For: SEMICONDUCTOR DIE
PACKAGE HAVING TWO
DIE PADDLES

Examiner: Hoai V Pham

Atty. Dkt.: 5500-79302

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date indicated below:

B. Noël Kivlin
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August 26, 2005
Date

Signature

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In response to the Office Action mailed July 26, 2005, please amend the above-identified application as follows.